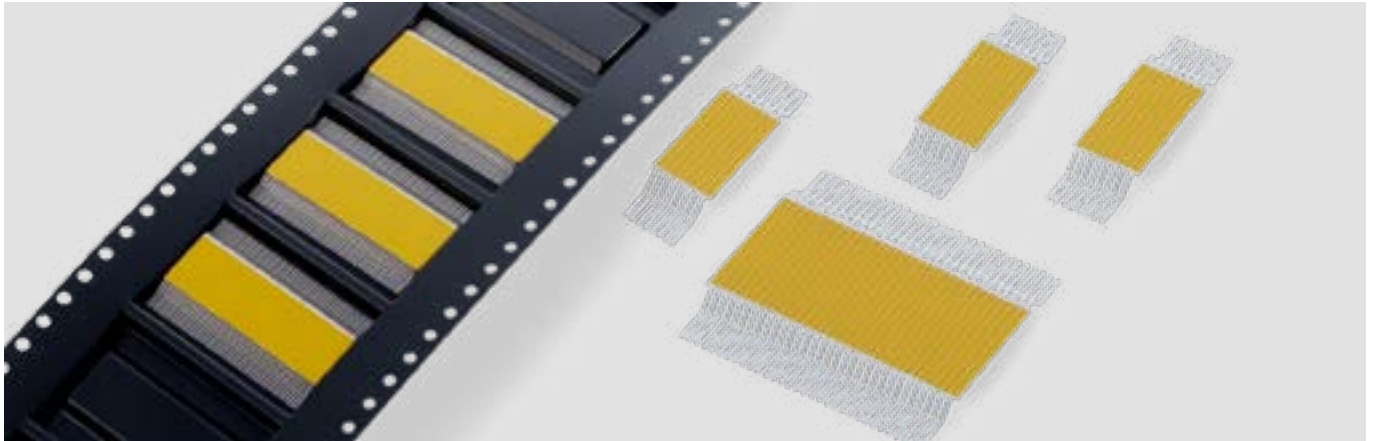


# PANTA<sup>®</sup> SMD



The **PANTA<sup>®</sup> SMD SYSTEM** is specially designed for use in automated assembly. It offers the user a wide range of placement options in the manufacture of electronic devices, even in difficult mounting situations.

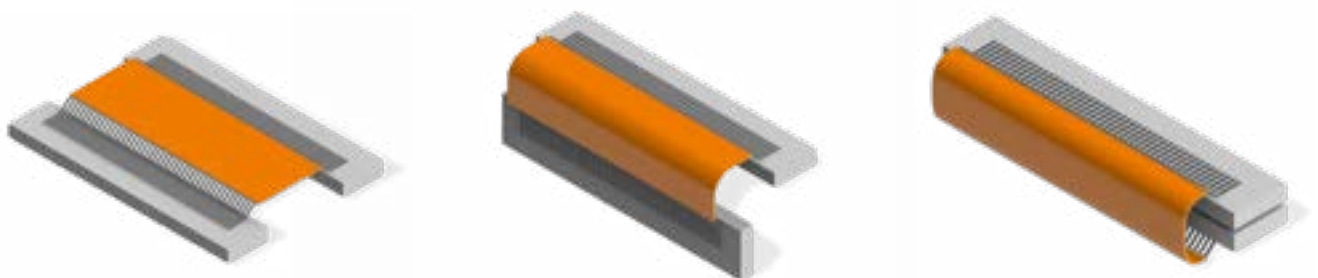
SMD components are a reliable and robust connection technology suitable for all standard assembly techniques. They also allow very dense board assembly.

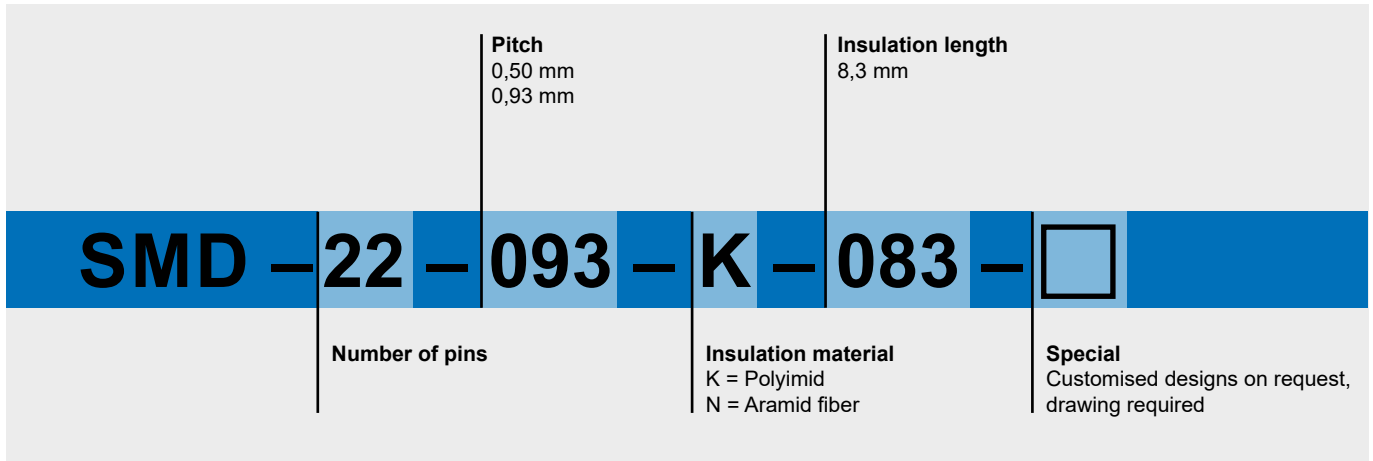
[Please ask for our processing instructions for PANTA<sup>®</sup> SMD System.](#)

## FEATURES

- Widely used in automotive, industrial electronics and medical applications
- Fulfills part accuracy and tolerance requirements for standard pick and place machines
- Temperature resistance from -40°C to +125°C (higher temperatures available on request)
- Current rating 1-2 A
- Vibration resistance
- Meets ISO 16232 and VDA 19.1 cleanliness requirements
- Processing according to standard solder profiles to DIN EN 61760-1 / J-STD-020
- Final assembly of connected PCBs up to 180° possible

## SMD EXAMPLES OF INSTALLATION SITUATIONS





CODE	DESCRIPTION		
P	Pitch (mm)	0,5	0,93
N	Number of pins (min. - max.)	8 - 32	4 - 25
BW	Bridging length (mm)	11,2	11,2
TL	Total length (mm)	15,2 ±0,2	15,2 ±0,2
CP	Coplanarity (µm)	100	150
IN	Insulation	Polyimid (PI)	
	Conductor material (mm)	Cu Ø0,1	Cu Ø0,15
	Conductor surface	NiSn	Sn / NiSn
RM	Min. Bending radius (mm)	2,0	2,0
BC	Max. Bending change	5 x 180°	5 x 180°
I	Current carrying capacity at RT (A)	1,0	2,0
U <sub>DC</sub>	Voltage rating (V <sub>DC</sub> )	30	60
OT	Operation temperature (°C)	-40 up to +125	-40 up to +125
FR	Flame retardant	UL 94 V-0	UL 94 V-0
SP	Recommended Reflow Profile	DIN EN 61760-1 / J-STD-020 LEVEL 1	
RC	Reflow cycles (max.)	2	2
	Packing (ESD)	IEC 60268-3 / EIA-481-E	
SC	Storage conditions	6 months / 10°C to 40°C / 40% to 60% rel. H.	

Customer specials on request.